

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|---------|---|---------------------------|------------------|---------|------------------|
| L1 | 140262 | (printed adj circuit adj board\$1) or pcb | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:00 |
| L2 | 3070782 | press\$3 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:00 |
| L3 | 184665 | (plating or electroless or electroplat\$3 or electro-plat\$3) | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:01 |
| L4 | 554172 | copper or cu | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:02 |
| L5 | 166498 | multilayer\$1 or multi-layer\$1 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:02 |
| L6 | 1225235 | releas\$3 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:02 |
| L7 | 23537 | (conduct\$3 or metal) near2 paste\$1 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:03 |
| L8 | 52139 | 3 same 4 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:03 |
| L9 | 957732 | insulat\$3 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:04 |
| L10 | 1401 | 1 and 2 and 6 and 8 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:05 |
| L11 | 84 | 5 and 7 and 10 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:05 |
| L12 | 2782971 | heat\$3 or thermal\$3 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:05 |
| L13 | 703353 | 2 same 12 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:05 |
| L14 | 381422 | etch\$3 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:06 |
| L15 | 883 | 10 and 13 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:07 |

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|-----|-----|-----------|---------------------------------|----|-----|------------------|
| L16 | 717 | 14 and 15 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:07 |
| L17 | 657 | 16 not 11 | US-PGPUB; USPAT; EPO; JPO | OR | OFF | 2004/12/20 14:07 |